# NST848BF3T5G

# NPN General Purpose Transistor

The NST848BF3T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-1123 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

## Features

- h<sub>FE</sub>, 200–450
- Low  $V_{CE(sat)}$ ,  $\leq 0.25 \text{ V}$
- Reduces Board Space
- This is a Halide–Free Device
- This is a Pb–Free Device

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	30	Vdc
Collector – Base Voltage	V <sub>CBO</sub>	30	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	100	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 1)	290 2.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	432	°C/W
Total Device Dissipation, T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 2)	347 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	360	°C/W
Thermal Resistance, Junction-to-Lead 3	R <sub>ΨJL</sub> (Note 2)	143	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

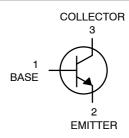
1. 100 mm<sup>2</sup> 1 oz, copper traces.

2. 500 mm<sup>2</sup> 1 oz, copper traces.



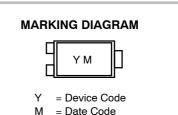
## **ON Semiconductor®**

#### http://onsemi.com



NST848BF3T5G





#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NST848BF3T5G	SOT-1123 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

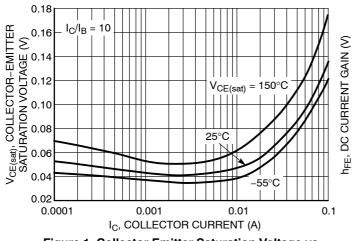
Ch	aracteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector - Emitter Breakdown Volt	age (I <sub>C</sub> = 10 mA)	V <sub>(BR)CEO</sub>	30	-	-	V
Collector – Emitter Breakdown Volt	age (I <sub>C</sub> = 10 μA, V <sub>EB</sub> = 0)	V <sub>(BR)CES</sub>	30	-	-	V
Collector - Base Breakdown Voltag	e (I <sub>C</sub> = 10 μA)	V <sub>(BR)CBO</sub>	30	-	-	V
Emitter – Base Breakdown Voltage	(I <sub>E</sub> = 1.0 μA)	V <sub>(BR)EBO</sub>	5.0	-	-	V
Collector Cutoff Current	(V <sub>CB</sub> = 30 V) (V <sub>CB</sub> = 30 V, T <sub>A</sub> = 150°C)	I <sub>CBO</sub>	-	_	15 5.0	nA μA

### **ON CHARACTERISTICS**

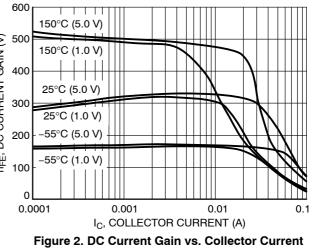
	h <sub>FE</sub>	_ 200	150 290	_ 450	-
Collector – Emitter Saturation Voltage (I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0.5 mA) (I <sub>C</sub> = 100 mA, I <sub>B</sub> = 5.0 mA)	V <sub>CE(sat)</sub>	-	-	0.25 0.6	V
Base – Emitter Saturation Voltage (I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0.5 mA) (I <sub>C</sub> = 100 mA, I <sub>B</sub> = 5.0 mA)	V <sub>BE(sat)</sub>	-	0.7 0.9	-	V
$\begin{array}{l} \text{Base-Emitter Voltage (I_C = 2.0 mA, V_{CE} = 5.0 V)} \\ \text{(I_C = 10 mA, V_{CE} = 5.0 V)} \end{array}$	V <sub>BE(on)</sub>	580 -	660 -	700 770	mV

#### SMALL-SIGNAL CHARACTERISTICS

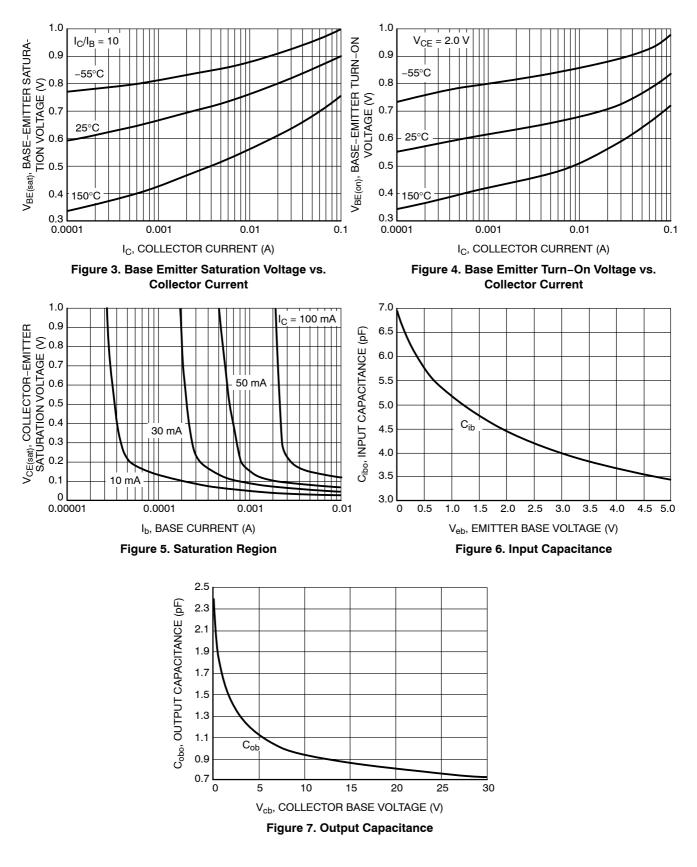
Current – Gain – Bandwidth Product $(I_{C} = 10 \text{ mA}, V_{CE} = 5.0 \text{ Vdc}, f = 100 \text{ MHz})$	f <sub>T</sub>	100	-	_	MHz
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	C <sub>obo</sub>	-	-	4.5	pF
Input Capacitance ( $V_{EB}$ = 0.5 V, $I_C$ = 0 mA, f = 1.0 MHz)	C <sub>ibo</sub>	-	-	10	pF
Noise Figure (I <sub>C</sub> = 0.2 mA, V <sub>CE</sub> = 5.0 Vdc, R <sub>S</sub> = 2.0 k $\Omega$ , f = 1.0 kHz, BW = 200 Hz)	NF	-	-	10	dB





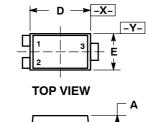


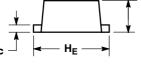
## NST848BF3T5G



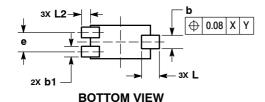
#### PACKAGE DIMENSIONS

SOT-1123 CASE 524AA ISSUE C









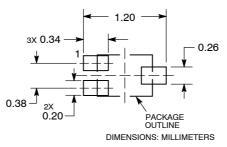
NOTES

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE З.
- MINIMUM THICKNESS OF BASE MATERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE 4.

MOL	D FLASI	1, PROT	ŀ			
IBUR	RRS.					
	MILLIM	MILLIMETERS				
DIM	MIN	MAX				
Α	0.34	0.40				
b	0.15	0.28				
b1	0.10	0.20				
С	0.07	0.17				
D	0.75	0.85				
E	0.55	0.65				
е	0.35	0.40				
HE	0.95	1.05				
L	0.185 REF					
L2	0.05	0.15				

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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